

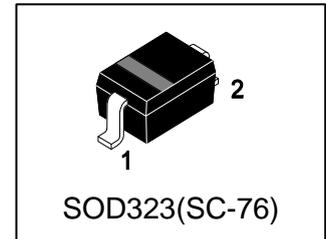
LMDL914T1G

S-LMDL914T1G

High –Speed Switching Diode

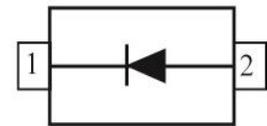
1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.



2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LMDL914T1G	5D	3000/Tape&Reel
LMDL914T3G	5D	10000/Tape&Reel



3. MAXIMUM RATINGS(Ta = 25°C)

Parameter	Symbol	Limits	Unit
Reverse Voltage	VR	100	V
Forward Current	IF	200	mA
Peak Forward Surge Current	IFMS	500	mA

4. THERMAL CHARACTERISTICS

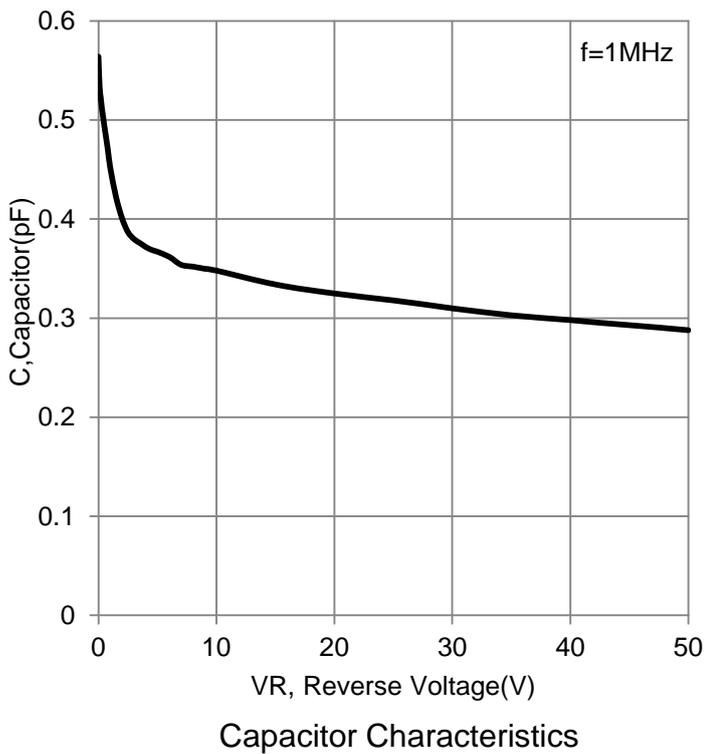
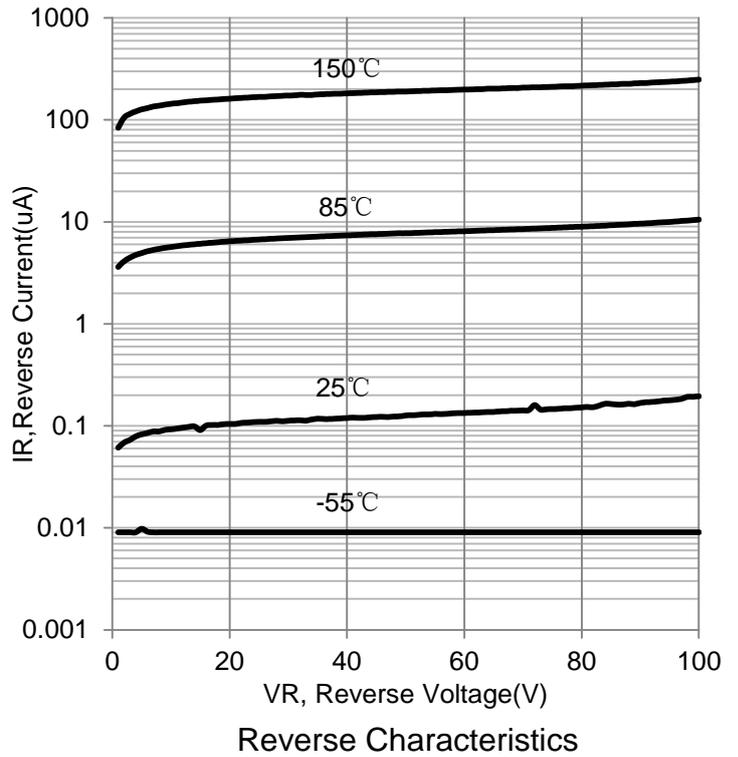
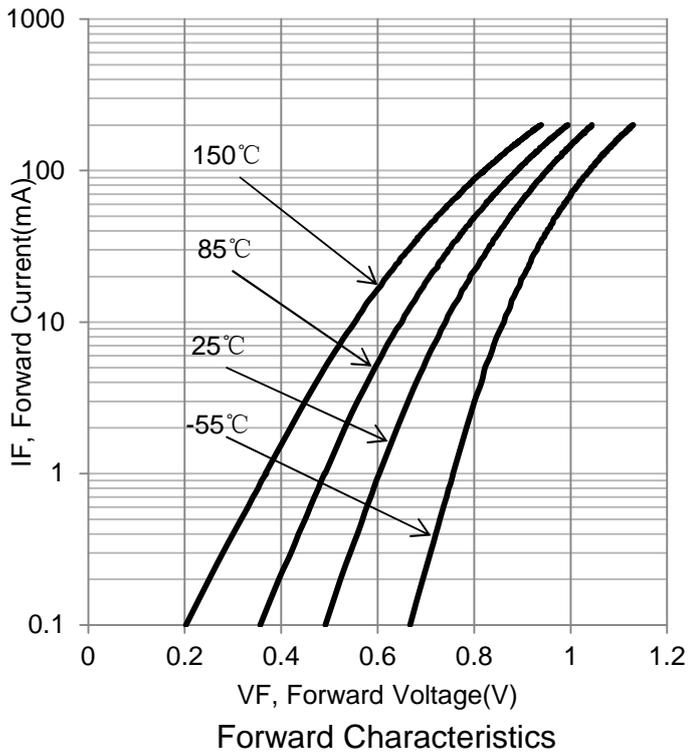
Parameter	Symbol	Limits	Unit
Total Device Dissipation, FR-4 Board (Note 1) @ TA = 25°C Derate above 25°C	PD	200 1.57	mW mW/°C
Thermal Resistance, Junction-to-Ambient(Note 1)	ROJA	635	°C/W
Junction and Storage temperature	TJ,Tstg	-55~+150	°C

1. FR-4 = 1.0×0.75×0.062 in.

5. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Reverse Breakdown Voltage (IR = 100µA)	VBR	100	-	-	V
Reverse Voltage Leakage Current (VR = 20V)	IR	-	-	25	nA
(VR = 75V)		-	-	5	µA
Diode Capacitance (VR = 0, f = 1.0 MHz)	CT	-	-	4	pF
Forward Voltage (IF = 10 mA)	VF	-	-	1	V
(IF = 50 mA)		-	-	1	
Reverse Recovery Time (IF = IR = 10 mA)	trr	-	-	4	ns
Non-Repetitive Peak Forward Current (square wave;Tj=25 °C prior to surge t=1 µs)	IFSM	-	-	4	A
(t=1ms)		-	-	1	
(t=1s)		-	-	0.5	

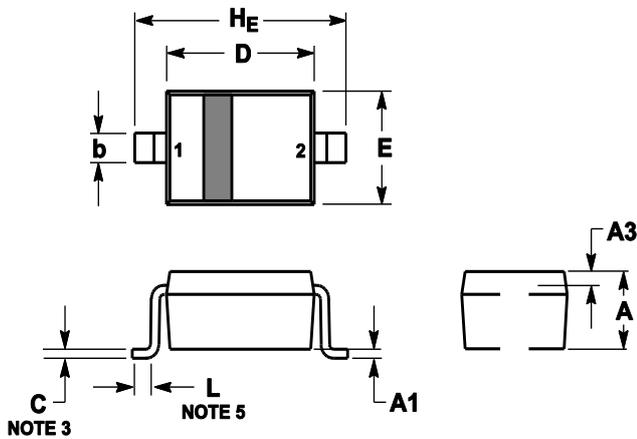
6. ELECTRICAL CHARACTERISTICS CURVES



7.OUTLINE AND DIMENSIONS

Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.8	0.9	1	0.031	0.035	0.04
A1	0	0.05	0.1	0	0.002	0.004
A3	0.15REF			0.006REF		
b	0.25	0.32	0.4	0.01	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.6	1.7	1.8	0.062	0.066	0.07
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
H_E	2.3	2.5	2.7	0.09	0.098	0.105

8.SOLDERING FOOTPRINT

